

Notice of References Cited	Application/Control No. 09/773,522	Applicant(s)/Patent Under Reexamination FARRAR ET AL.	
	Examiner Brian K Talbot	Art Unit 1762	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-4,828,886	05-1989	Hieber, Hartmann	427/422
	B	US-5,229,016	07-1993	Hayes et al.	222/590
	C	US-5,377,902	01-1995	Hayes, Donald J.	228/254
	D	US-5,681,757	10-1997	Hayes, Donald J.	257/778
	E	US-6,196,443	03-2001	DiGiacomo, Giulio	228/180.22
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Microjet Printing of Solder and Polymers for Multi-chip Modules and Chip-scale Packages, MicroFab Technologies, IMPAS 199
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.